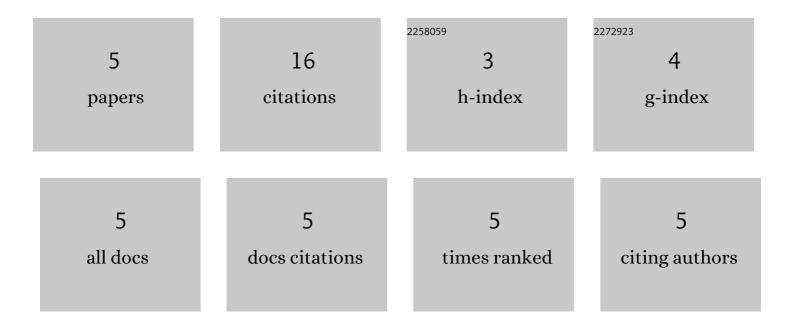
Fengwei Wang

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/4660053/publications.pdf Version: 2024-02-01



#	Article	IF	CITATIONS
1	Improving the electrical and mechanical performances of embedded capacitance materials by introducing tungsten disulfide nanoflakes into the dielectric layer. Journal of Materials Science: Materials in Electronics, 2020, 31, 7889-7897.	2.2	2
2	Improving the film-forming ability of BaTiO3/epoxy resin suspension by adjusting the solvent composition for the fabrication of embedded capacitance materials. Journal of Materials Science: Materials in Electronics, 2019, 30, 7743-7751.	2.2	2
3	Influences of filler dispersity in epoxy resin on the electrical and mechanical performances of embedded capacitance materials. Journal of Materials Science: Materials in Electronics, 2018, 29, 17939-17947.	2.2	3
4	Influences of copper roughness on the electrical and mechanical performances of embedded capacitance materials. Journal of Adhesion Science and Technology, 2016, 30, 1364-1369.	2.6	4
5	Embedded thin film resistors fabricated by alkaline electroless deposition. Journal of Materials Science: Materials in Electronics, 2015, 26, 9766-9775.	2.2	5